

Title (en)
Interconnection structure including blind via holes intended for being metallised

Title (de)
Verbindungsstruktur, die Sacklöcher umfasst, die metallisiert werden sollen

Title (fr)
Structure d'interconnexion comprenant des vias borgnes destinés à être métallisés

Publication
EP 2365743 B1 20170719 (FR)

Application
EP 11157130 A 20110307

Priority
FR 1051727 A 20100310

Abstract (en)
[origin: EP2365743A2] The structure (100) has a substrate (102) whose face (110) is integrated to a face (111) of another substrate (104). An electric contact (114) is arranged against the face of the latter substrate and next to a blind via (108) and/or against the face and/or another face (112) of the former substrate. A channel (116) provides communication of the via with an environment outside of the structure and/or with a cavity formed in the structure. The channel extends parallel to one of the faces of the substrates. An independent claim is also included for a method for realization of an interconnection structure.

IPC 8 full level
H05K 3/40 (2006.01); **H01L 21/60** (2006.01); **H01L 21/768** (2006.01); **H01L 23/48** (2006.01)

CPC (source: EP US)
H01L 21/76898 (2013.01 - EP US); **H01L 23/481** (2013.01 - EP US); **H01L 24/24** (2013.01 - EP US); **H01L 24/92** (2013.01 - EP US); **H01L 2224/24226** (2013.01 - EP US); **H01L 2224/24992** (2013.01 - EP US); **H01L 2224/24997** (2013.01 - EP US); **H01L 2224/30151** (2013.01 - EP US); **H01L 2224/32225** (2013.01 - EP US); **H01L 2224/82** (2013.01 - EP US); **H01L 2224/8203** (2013.01 - EP US); **H01L 2224/82101** (2013.01 - EP US); **H01L 2224/83** (2013.01 - EP US); **H01L 2224/83192** (2013.01 - EP US); **H01L 2224/8385** (2013.01 - EP US); **H01L 2224/9202** (2013.01 - EP US)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
EP 2365743 A2 20110914; **EP 2365743 A3 20160323**; **EP 2365743 B1 20170719**; FR 2957481 A1 20110916; FR 2957481 B1 20120831; JP 2011187964 A 20110922; US 2011221068 A1 20110915; US 8482130 B2 20130709

DOCDB simple family (application)
EP 11157130 A 20110307; FR 1051727 A 20100310; JP 2011051734 A 20110309; US 201113031917 A 20110222